

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IPD30N10S3L-34	**Issued**	03. June 2021
MA#	MA003185326		
Package	PG-TO252-3-11	**Weight***	371.52 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.345	0.63	0.63	6311	6311
leadframe	inorganic material	phosphorus	7723-14-0	0.065	0.02		174	
	non noble metal	iron	7439-89-6	0.215	0.06		580	
	non noble metal	copper	7440-50-8	215.017	57.87	57.95	578752	579506
wire	non noble metal	aluminium	7429-90-5	3.103	0.84	0.84	8353	8353
encapsulation	inorganic material	zincoxide	1314-13-2	1.251	0.34		3366	
	miscellaneous	miscellaneous	-	6.253	1.68		16830	
	plastics	epoxy resin	-	18.758	5.05		50491	
	inorganic material	silicondioxide	60676-86-0	98.794	26.59	33.66	265919	336606
leadfinish	non noble metal	tin	7440-31-5	3.740	1.01	1.01	10067	10067
plating	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	nickel	7440-02-0	0.091	0.02	0.02	244	245
solder	non noble metal	tin	7440-31-5	0.054	0.01		144	
	noble metal	silver	7440-22-4	0.067	0.02		181	
	non noble metal	lead	7439-92-1	2.563	0.69	0.72	6900	7225
heatspreader	inorganic material	phosphorus	7723-14-0	0.006			16	
	non noble metal	iron	7439-89-6	0.019	0.01		52	
	non noble metal	copper	7440-50-8	19.177	5.16	5.17	51619	51687
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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